



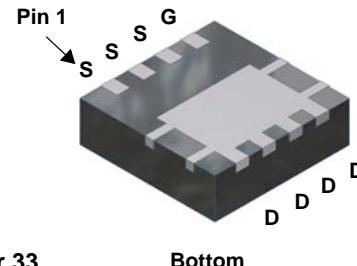
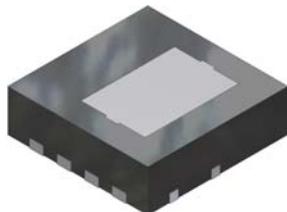
FDMC2514SDC

N-Channel Dual Cool™ PowerTrench® SyncFET™

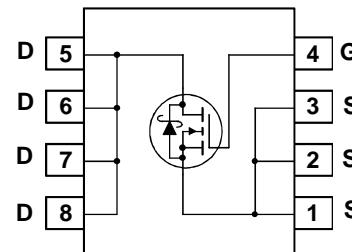
25 V, 40 A, 3.5 mΩ

Features

- Dual Cool™ Top Side Cooling PQFN package
- Max $r_{DS(on)}$ = 3.5 mΩ at $V_{GS} = 10$ V, $I_D = 22.5$ A
- Max $r_{DS(on)}$ = 4.7 mΩ at $V_{GS} = 4.5$ V, $I_D = 18$ A
- High performance technology for extremely low $r_{DS(on)}$
- SyncFET Schottky Body Diode
- RoHS Compliant



Top Power 33 Bottom



MOSFET Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DS}	Drain to Source Voltage	25	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	40	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	106	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	24	
	-Pulsed	200	
E_{AS}	Single Pulse Avalanche Energy	84	mJ
dv/dt	Peak Diode Recovery dv/dt	2.0	V/ns
P_D	Power Dissipation $T_C = 25^\circ\text{C}$	60	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	3.0	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics

$R_{θJC}$	Thermal Resistance, Junction to Case (Top Source)	5.8	°C/W
$R_{θJC}$	Thermal Resistance, Junction to Case (Bottom Drain)	2.1	
$R_{θJA}$	Thermal Resistance, Junction to Ambient (Note 1a)	42	
$R_{θJA}$	Thermal Resistance, Junction to Ambient (Note 1b)	105	
$R_{θJA}$	Thermal Resistance, Junction to Ambient (Note 1i)	17	
$R_{θJA}$	Thermal Resistance, Junction to Ambient (Note 1j)	26	
$R_{θJA}$	Thermal Resistance, Junction to Ambient (Note 1k)	12	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
2514S	FDMC2514SDC	Dual Cool™ Power 33	13"	12 mm	3000 units

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	25			V
$\frac{\Delta \text{BV}_{\text{DSS}}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 10 \text{ mA}$, referenced to 25°C		21		$\text{mV}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			500	μA
I_{GSS}	Gate to Source Leakage Current, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA

On Characteristics

$V_{GS(\text{th})}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 1 \text{ mA}$	1.2	1.7	3.0	V
$\frac{\Delta V_{GS(\text{th})}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 10 \text{ mA}$, referenced to 25°C		-5		$\text{mV}/^\circ\text{C}$
$r_{DS(\text{on})}$	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 22.5 \text{ A}$		2.5	3.5	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}, I_D = 18 \text{ A}$		3.6	4.7	
		$V_{GS} = 10 \text{ V}, I_D = 22.5 \text{ A}, T_J = 125^\circ\text{C}$		3.5	4.5	
g_{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_D = 22.5 \text{ A}$		122		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 13 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		2031	2705	pF
C_{oss}	Output Capacitance			596	795	pF
C_{rss}	Reverse Transfer Capacitance			134	205	pF
R_g	Gate Resistance			1.1	2.4	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 13 \text{ V}, I_D = 22.5 \text{ A}, V_{GS} = 10 \text{ V}, R_{\text{GEN}} = 6 \Omega$		11	22	ns
t_r	Rise Time			3.6	10	ns
$t_{d(off)}$	Turn-Off Delay Time			26	41	ns
t_f	Fall Time			3	10	ns
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ V} \text{ to } 10 \text{ V}$		31	44	nC
Q_g	Total Gate Charge		$V_{GS} = 0 \text{ V} \text{ to } 4.5 \text{ V}$	14	20	nC
Q_{gs}	Gate to Source Gate Charge		$V_{DD} = 13 \text{ V}, I_D = 22.5 \text{ A}$		6.5	nC
Q_{gd}	Gate to Drain "Miller" Charge				3.9	nC

Drain-Source Diode Characteristics

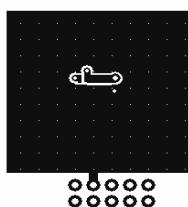
V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 22.5 \text{ A}$ (Note 2)		0.79	1.2	V
		$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)		0.47	0.8	
t_{rr}	Reverse Recovery Time	$I_F = 22.5 \text{ A}, di/dt = 300 \text{ A}/\mu\text{s}$		24	39	ns
				19	34	

Thermal Characteristics

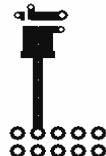
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Top Source)	5.8	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Bottom Drain)	2.1	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	42	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	105	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1c)	29	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1d)	40	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1e)	19	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1f)	23	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1g)	30	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1h)	79	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1i)	17	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1j)	26	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1k)	12	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1l)	16	

NOTES:

1. $R_{\theta JA}$ is determined with the device mounted on a FR-4 board using a specified pad of 2 oz copper as shown below. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 42 °C/W when mounted on
a 1 in² pad of 2 oz copper



b. 105 °C/W when mounted on
a minimum pad of 2 oz copper

- c. Still air, 20.9x10.4x12.7mm Aluminum Heat Sink, 1 in² pad of 2 oz copper
 - d. Still air, 20.9x10.4x12.7mm Aluminum Heat Sink, minimum pad of 2 oz copper
 - e. Still air, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in² pad of 2 oz copper
 - f. Still air, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
 - g. 200FPM Airflow, No Heat Sink, 1 in² pad of 2 oz copper
 - h. 200FPM Airflow, No Heat Sink, minimum pad of 2 oz copper
 - i. 200FPM Airflow, 20.9x10.4x12.7mm Aluminum Heat Sink, 1 in² pad of 2 oz copper
 - j. 200FPM Airflow, 20.9x10.4x12.7mm Aluminum Heat Sink, minimum pad of 2 oz copper
 - k. 200FPM Airflow, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, 1 in² pad of 2 oz copper
 - l. 200FPM Airflow, 45.2x41.4x11.7mm Aavid Thermalloy Part # 10-L41B-11 Heat Sink, minimum pad of 2 oz copper
2. Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.
3. E_{AS} of 84 mJ is based on starting $T_J = 25$ °C, $L = 1$ mH, $I_{AS} = 13$ A, $V_{DD} = 23$ V, $V_{GS} = 10$ V. 100% test at $L = 0.3$ mH, $I_{AS} = 20$ A.
4. As an N-ch device, the negative V_{GS} rating is for low duty cycle pulse occurrence only. No continuous rating is implied.
5. $I_{SD} \leq 22.5$ A, $di/dt \leq 200$ A/µs, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25$ °C.

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

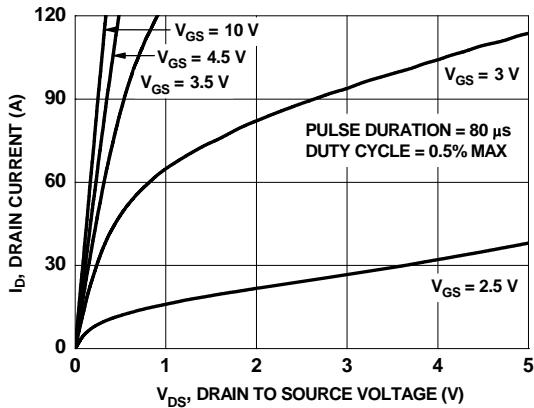


Figure 1. On-Region Characteristics

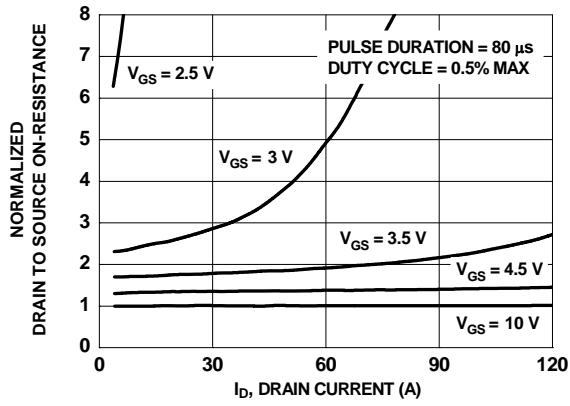


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

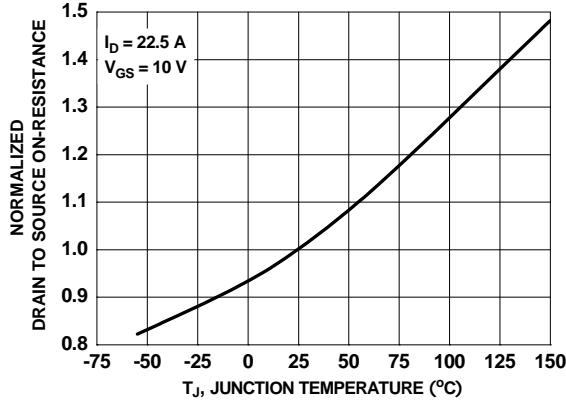


Figure 3. Normalized On-Resistance vs Junction Temperature

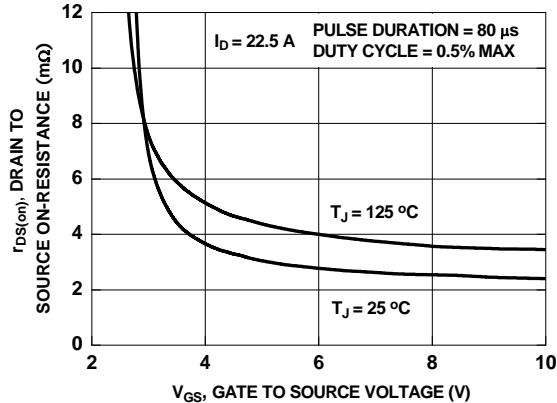


Figure 4. On-Resistance vs Gate to Source Voltage

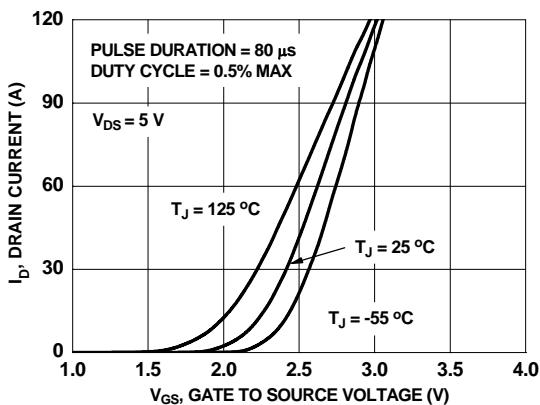


Figure 5. Transfer Characteristics

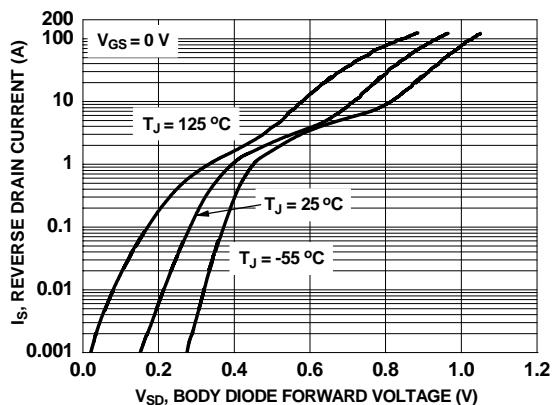


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

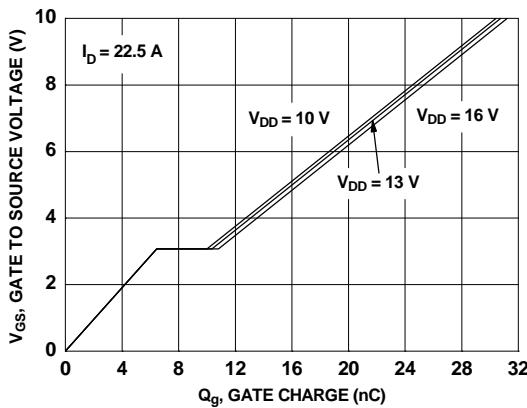


Figure 7. Gate Charge Characteristics

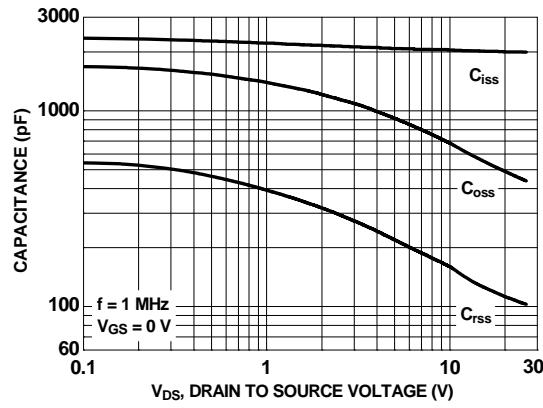


Figure 8. Capacitance vs Drain to Source Voltage

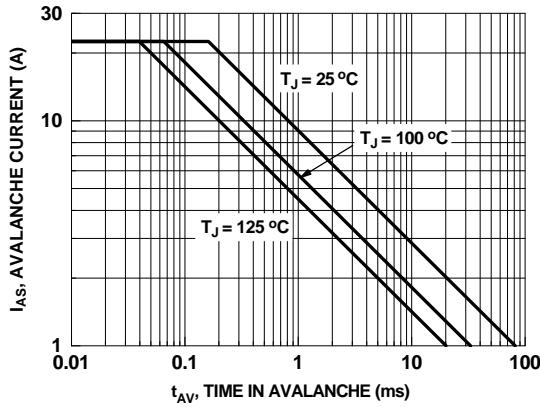


Figure 9. Unclamped Inductive Switching Capability

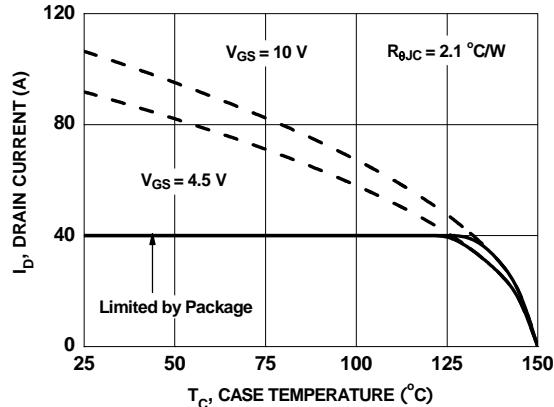


Figure 10. Maximum Continuous Drain Current vs Case Temperature

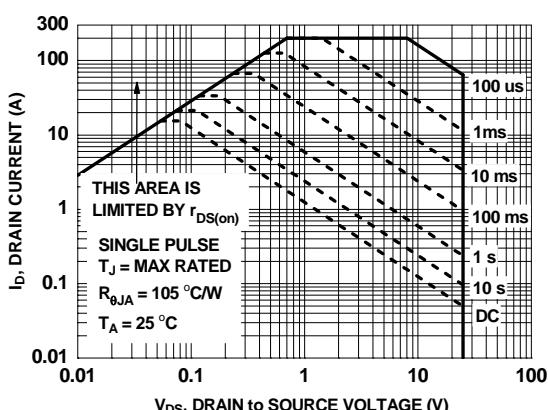


Figure 11. Forward Bias Safe Operating Area

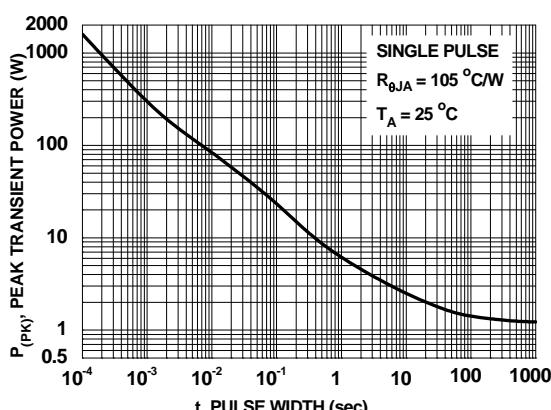


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

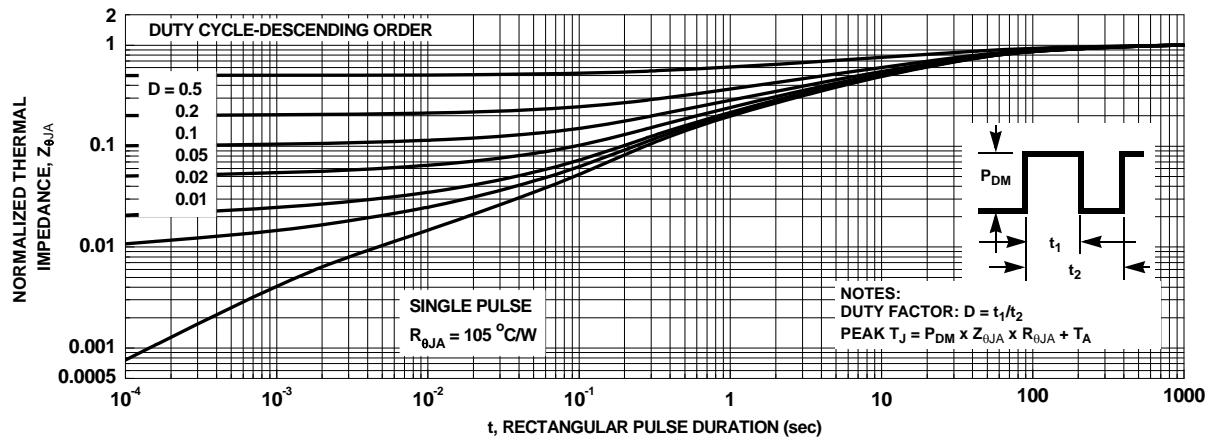


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (continued)

SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 13 shows the reverse recovery characteristic of the FDMC2514SDC.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

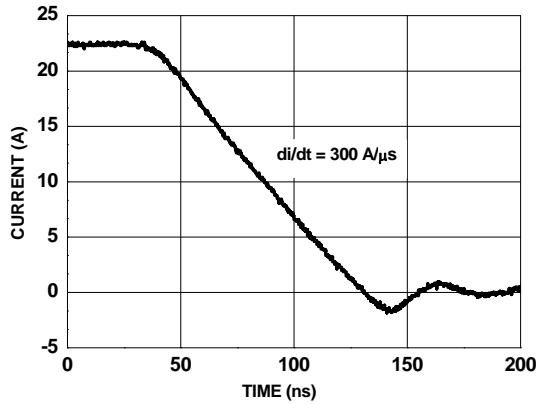


Figure 14. FDMC2514SDC SyncFET body diode reverse recovery characteristic

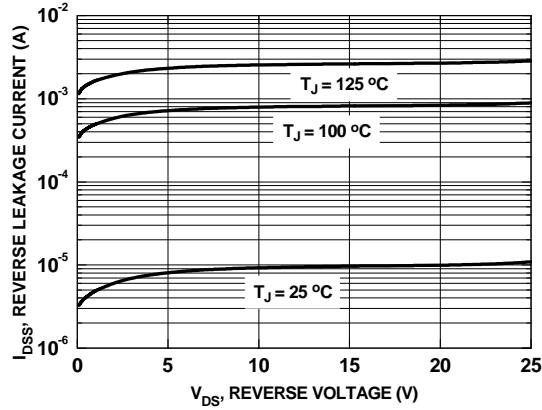
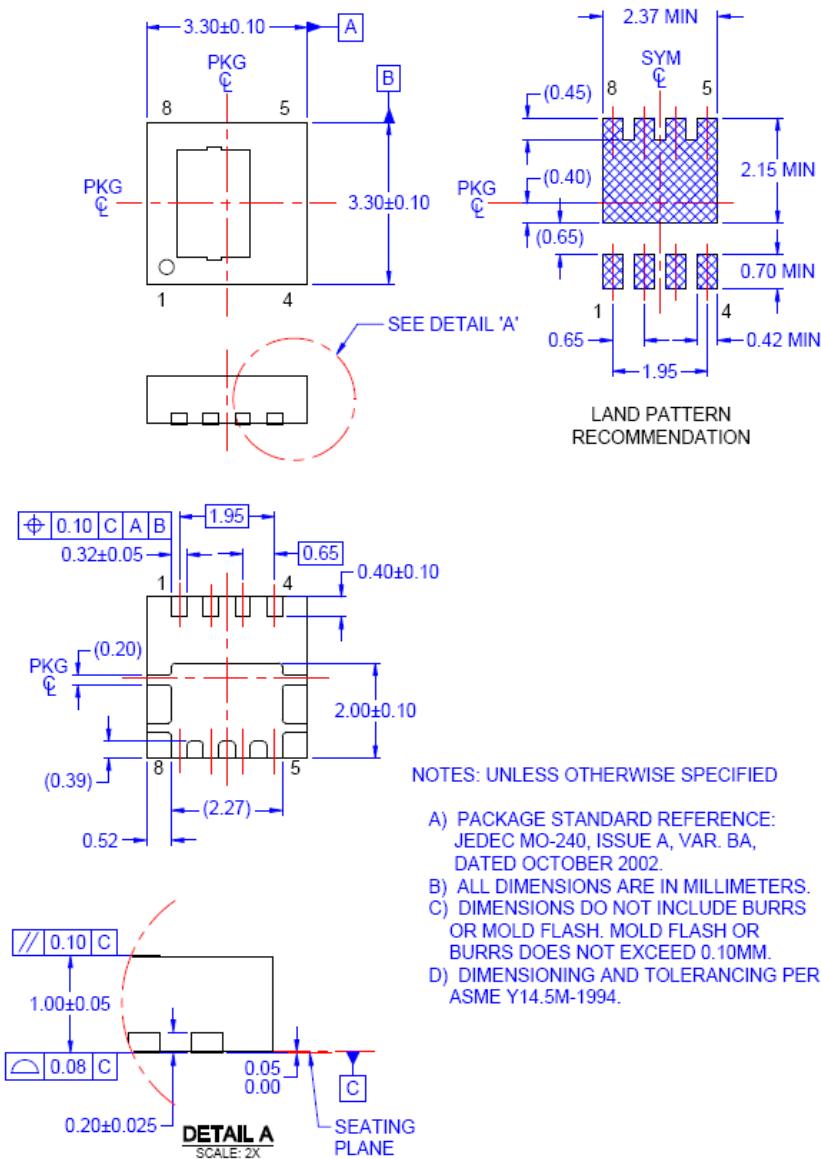


Figure 15. SyncFET body diode reverse leakage versus drain-source voltage

Dimensional Outline and Pad Layout





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